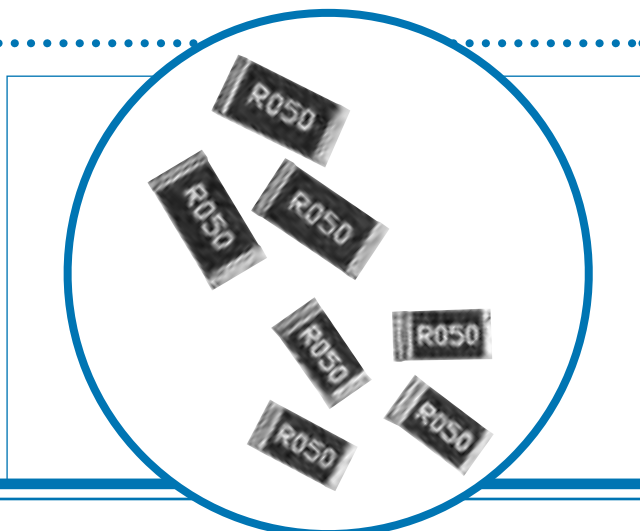


Low Value Flat Chip Resistor

LRC/LRF Series

- Standard 2512, 2010 and 1206 sizes
- Resistance values down to 0.003 ohms
- Leach resistant solder-plated copper wrap-around termination
- Low inductance - less than 0.2nH
- AEC-Q200 Qualified



Electrical Data

		LR1206	LR2010	LR2512
Power rating at 70°C	watts	0.5	1.0	1.5/2.0*
Resistance range	ohms	0R010 to 1R	0R003 to 1R	0R003 to 1R
Dielectric withstanding voltage	volts	200	200	200
TCR	ppm/°C	±100 (Contact factory for value below 0.050 ohms)		
Resistance tolerance	%	≤R005 5%, >R005 1, 2, 5%		
Temperature rise at rated power	°C	40	80	90
Pad and trace area for max power rating @ 70°C	mm ²	30	30	100

*2 Watts with total solder pad and trace size of 300 mm²

Physical Data

Dimensions (mm)					
Size	L	W	H (max)	D	D1
LR1206	3.20±0.305	1.63±0.203	0.8	0.48±0.25	0.48±0.25
LR2010	5.23±0.38	2.64±0.25	0.8	0.48±0.25	0.48±0.25
LR2512	6.50±0.38	3.25±0.25	0.8	0.48±0.25	0.48±0.25

LR 1206 / 2010 / 2512

General Note

Welwyn Components reserves the right to make changes in product specification without notice or liability. All information is subject to Welwyn's own data and is considered accurate at time of going to print.

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Telephone: +44 (0) 1670 822181 · Facsimile: +44 (0) 1670 829465 · Email: info@welwyn-tt.com · Website: www.welwyn-tt.com

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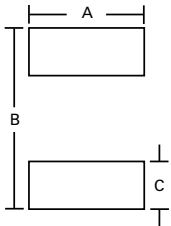
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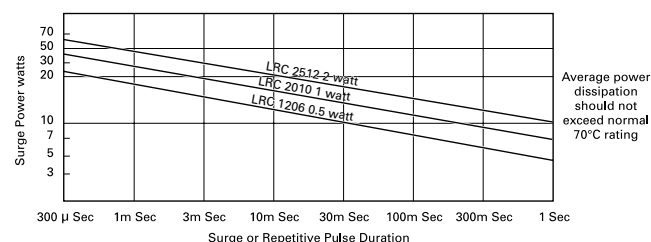
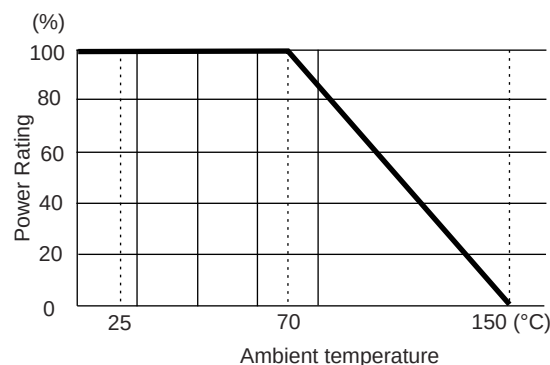
Low Value Flat Chip Resistor

LRC/LRF Series

Dimensions (mm)			
	A	B	C
LR1206	2.0	4.0	1.25
LR2010	3.05	6.5	1.5
LR2512	3.7	7.75	1.5



AEC-Q200 Table 7		Method	Max.		Typ.
ref	Test		(add R05)		
3	High Temp. Exposure	MIL-STD-202 Method 108	ΔR%	0.5	0.2
4	Temperature Cycling	JESD22 Method JA-104	ΔR%	0.25	0.1
6	Moisture Resistance	MIL-STD-202 Method 106	ΔR%	0.5	0.2
7	Biased Humidity	MIL-STD-202 Method 103	ΔR%	0.5	0.2
8	Operational Life (Cyclic Load)	MIL-STD-202 Method 108	ΔR%	1	0.5
14	Vibration	MIL-STD-202 Method 204	ΔR%	0.5	0.05
15	Resistance to Soldering Heat	MIL-STD-202 Method 210	ΔR%	0.25	0.05
16	Thermal Shock	MIL-STD-202 Method 107	ΔR%	0.25	0.1
18	Solderability	J-STD-002	>95% coverage		
21	Board Flex	AEC-Q200-005	ΔR%	0.5	0.2
22	Terminal Strength	AEC-Q200-006	ΔR%	0.25	0.1
	Short Term Overload	6.25 x Pr for 2s	ΔR%	0.5	
	Low Temperature Storage	-65°C for 100 hours	ΔR%	0.5	
	Leach Resistance	Solder dip at 250°C	90s minimum		



Note:

- Although 2010 and 2512 sizes have passed temperature cycling and thermal shock, it is in general not recommended that ceramic chips this large be used on FR4 in a severe temperature cycle environment due to the possibility of solder joint fatigue.
- Full AEC-Q200 qualification applies to ohmic values $\geq R01$.

Ordering Procedure

Example: LRF2512 at 10 milliohms (hence flip-chip mounted) and 2% tolerance on a reel of 1800 pieces

L R F 2 5 1 2 - R 0 1 G W

Type _____

Mounting _____

	Conventional (element up)	Values > R025
F	Flip-chip (element down)	Values ≤ R025

Size _____

Value (use IEC62 code) _____

Tolerance (use IEC62 code) _____

F	1%
G	2%
J	5%

Packing _____

W	Tape	1206 or 2010	3000/reel	Standard
		2512	1800/reel	
T1		All sizes	1000/reel	